

DIL
EMU CRITICAL ITEMS LIST

12/24/94 SUPSEDES 12/24/93

ANALYST:

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NAME P/N QTY	CRIT	FAILURE MODE & CAUSES	FAILURE EFFECT	RATIONALE FOR ACCEPTANCE
DCM ELECTRONICS, ITEM 350 SV792291-27 (1)	2/1RB	350FN33: +5.6V power supply drifts low. CAUSE: Semiconductor failure.	EMD ITEM: Improper supply to DCM display and logic circuitry. Possible loss of DCM microprocessor and display. All DCM secondary voltages drift high. GFE INTERFACE: Possible loss of CWS logic functions. Possible unreadable messages. MISSION: None. CREW/VEHICLE: None for single failure. Possible loss of crewman with loss of CCC, oxygen, or low vent flow.	A. Design - Semiconductor failure is minimized through the use of high reliability components. Established reliability capacitors (Level S) and resistors (Level R) are used and are qualified to the requirements their respective MIL specs and thermal shocked per condition B of MIL-STD-202 Method 107. The transistors and diodes are qualified to the requirements of MIL-S-19500 and receive the burn-in of JANTKV level parts per the applicable methods, 1038, 1039, and 1040, of MIL-STD-750. The electronic components are operating within the power derating requirements of SVHS 7806. The printed circuit boards are polyimide per MIL-P-13949 Type GI and manufactured per SW-P-0006. Parts mounting and soldering is per MSFC-STD-136 and WHB5300-4 (3A-1). The board assemblies are hard mounted to the DCM case to provide a thermal transfer path between the board heat sinks and the case to direct heat away from the electronic components. The board assemblies are also conformal coated per MIL-A-46146 (Dow Corning RTV 3140) for environmental protection. All wiring used in the DCM is M22759/11 (teflon insulated). Soldering is per WHB5300. 4 (3A-1) and wire crimping is per SVHS 4909 (based on MSC-Spec-G-1A). All wires are strain relieved. Electrical connectors are environmentally sealed to prevent damage due to contamination and humidity. B. Test - In-Process: The DCM electronics assembly is tested during initial build-up at the board assembly level, after the PC boards and wiring, and after installation of the boards and wiring, and after installation of the front cover. These tests consists of continuity through the switches and wiring, voltage checks, functional check of all current limiters, and full operation of the DCM electronics. The tests insure proper operation of the DCM electronics. The tests insure proper operation of all electronic components. PDA: Vibration testing per SEMU-60-015 followed by continuity and

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2/1R8 350FM33:

full function testing verifies the integrity of the solder joints and crimp connections in the DCM. The random vibration level for this test is 6.5 grms for a duration of 1 minute per axis for each of the three orthogonal axes. (JSC-SPEC-SP-7-0023)

Thermal vacuum testing followed by full functional electrical testing per SEMU-60-015 also verifies the solder joints as well as the acceptability of the components. The DCM is placed in a vacuum chamber at 1×10^{-3} torr. The DCM case temperature is cycled 3 times from 70 to 130 degree F. At the end of the third cycle, the temperature is held between 130 to 135 degree F for a minimum of four hours. The DCM display must remain on throughout the test. This verifies proper transfer of heat from the electronics to the DCM case to prevent overheating of components.

Certification:

The liquid crystal display version of the DCM electronics Assembly (item 350, SV792291-7), as part of the full DCM item 300 (items 350 and 305 combined), was successfully subjected to levels of vibration and shock equivalent to those experienced over a fifteen (15) year life.

Random Flight Vibration	1.625 grms	48 min/axis
Sinusoidal Flight Vibration	1 grm	5-35 hz ea. axis
Design Shock	6.5 grms	11 ms/peak

The LED display version of the DCM electronics Assembly (item 350, SV792291-5) was subjected to certification testing between June and August of 1986 with the exception of EMI which occurred in September of 1985. The testing verified the basic integrity and flight worthiness of the redesign DCM configuration (item 300, SV 792296). The item 350 completed qualification vibration (7.8 grms, 6 minutes per axis) as a separate item, and structural vibration (1.625 grms, 48 minutes per axis), and shock testing as part of the full DCM item 300 (item 350 combined with item 305). The DCM/300 also completed the four hour thermal vacuum certification at 135 degree F and storage temperature testing at 35 degree F. No class 1 EC's have been incorporated into this version of the DCM since certification was completed.

CIL
EMU CRITICAL ITEMS LIST

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NAME P/N QTY	CRIT	FAILURE MODE & CAUSES	FAILURE EFFECT	RATIONALE FOR ACCEPTANCE
	2/1R0	35DFM33:		<p>C. Inspection - 100% inspection of all soldering PC boards and wiring by Hamilton Standard QA and DCAS QA. All board assemblies are inspected for damage and contamination. All wiring is inspected for damage, nicks in the insulation, wear, and strain relief.</p> <p>The DCM is internally inspected after installation of the circuit boards and wiring to insure no damage has occurred during assembly.</p> <p>D. Failure History - None.</p> <p>E. Ground Turnaround - Failure would be detected per FEMU-R-001, EMU Vacuum Performance Matrix, DCM Display Verification.</p> <p>F. Operational Use - Crew Response - Pre-EVA : When detected during scheduled status checks, discontinue use of EMU. Consider use of third EMU if available. EVA : When detected by ground or during periodic status check, terminate EVA. Special Training - Standard training covers this failure mode. Operational Considerations - EVA checklist procedures verify hardware integrity and systems operational status prior to EVA. Flight rules define operational EMU CWS as at least able to monitor a valid status list. Real Time Data System allows ground monitoring of EMU systems.</p>